

MOSFETs Silicon P-Channel MOS (U-MOSVI)

# SSM3J356R

#### 1. Applications

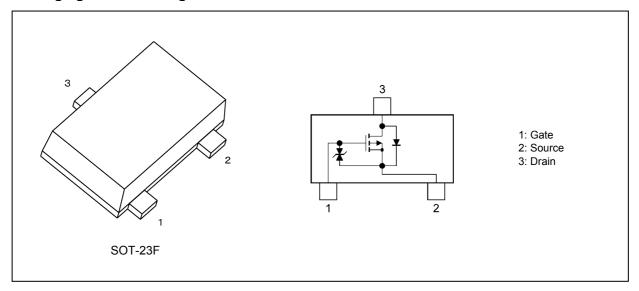
· Power Management Switches

#### 2. Features

- (1) AEC-Q101 qualified (Note 1)
- (2) 4 V gate drive voltage.
- (3) Low drain-source on-resistance
  - :  $R_{DS(ON)}$  = 400 m $\Omega$  (max) (@V<sub>GS</sub> = -4.0 V)  $R_{DS(ON)}$  = 300 m $\Omega$  (max) (@V<sub>GS</sub> = -10 V)
- (4) HBM: 2-kV class

Note 1: For detail information, please contact to our sales.

#### 3. Packaging and Pin Assignment





#### 4. Absolute Maximum Ratings (Note) (Unless otherwise specified, Ta = 25 °C)

|                        | Characteristics |            |                    | Symbol    | Rating     | Unit |
|------------------------|-----------------|------------|--------------------|-----------|------------|------|
| Drain-source voltage   |                 |            |                    | $V_{DSS}$ | -60        | V    |
| Gate-source voltage    |                 |            |                    | $V_{GSS}$ | -20/+10    |      |
| Drain current (DC)     |                 |            | (Note 1)           | $I_D$     | -2         | Α    |
| Drain current (pulsed) |                 |            | (Note 1), (Note 2) | $I_{DP}$  | -6         |      |
| Power dissipation      |                 |            | (Note 3)           | $P_{D}$   | 1          | W    |
| Power dissipation      | (               | (t ≤ 10 s) | (Note 3)           |           | 2          |      |
| Channel temperature    |                 |            |                    | $T_ch$    | 150        | ů    |
| Storage temperature    |                 | •          |                    | $T_{stg}$ | -55 to 150 |      |

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

- Note 1: Ensure that the channel temperature does not exceed 150 °C.
- Note 2: Repetitive rating; pulse width limited by maximum channel temperature.
- Note 3: Device mounted on a 25.4 mm × 25.4 mm × 1.6 mm FR4 glass epoxy board (Cu pad: 645 mm<sup>2</sup>)

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.

Note: The MOSFETs in this device are sensitive to electrostatic discharge. When handling this device, the worktables, operators, soldering irons and other objects should be protected against anti-static discharge.

Note: The channel-to-ambient thermal resistance, R<sub>th(ch-a)</sub>, and the drain power dissipation, P<sub>D</sub>, vary according to the board material, board area, board thickness and pad area. When using this device, be sure to take heat dissipation fully into account.



#### 5. Electrical Characteristics

## 5.1. Static Characteristics (Unless otherwise specified, T<sub>a</sub> = 25 °C)

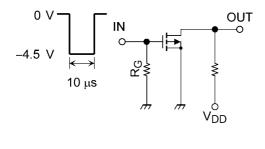
| Characteristics                |          | Symbol               | Test Condition                                       | Min  | Тур. | Max  | Unit |
|--------------------------------|----------|----------------------|--|------|------|------|------|
| Gate leakage current           |          | I <sub>GSS</sub>     | V <sub>GS</sub> = -16 V/+10 V, V <sub>DS</sub> = 0 V | _    | _    | ±10  | μА   |
| Drain cut-off current          |          | I <sub>DSS</sub>     | V <sub>DS</sub> = -60 V, V <sub>GS</sub> = 0 V       | _    | _    | -10  | μА   |
| Drain-source breakdown voltage |          | V <sub>(BR)DSS</sub> | I <sub>D</sub> = -1 mA, V <sub>GS</sub> = 0 V        | -60  | _    | _    | V    |
| Drain-source breakdown voltage | (Note 1) | V <sub>(BR)DSX</sub> | I <sub>D</sub> = -1 mA, V <sub>GS</sub> = 10 V       | -50  | _    | _    |      |
| Gate threshold voltage         |          | V <sub>th</sub>      | V <sub>DS</sub> = -10 V, I <sub>D</sub> = -1 mA      | -0.8 | _    | -2.0 | V    |
| Drain-source on-resistance     | (Note 2) | R <sub>DS(ON)</sub>  | I <sub>D</sub> = -1.0 A, V <sub>GS</sub> = -4.0 V    | _    | 280  | 400  | mΩ   |
|                                |          |                      | I <sub>D</sub> = -1.0 A, V <sub>GS</sub> = -4.5 V    | _    | 270  | 360  |      |
|                                |          |                      | I <sub>D</sub> = -1.0 A, V <sub>GS</sub> = -10 V     | _    | 240  | 300  |      |
| Forward transfer admittance    | (Note 2) | Y <sub>fs</sub>      | V <sub>DS</sub> = -10 V, I <sub>D</sub> = -1 A       | _    | 4.7  | _    | S    |

Note 1: If a reverse bias is applied between gate and source, this device enters  $V_{(BR)DSX}$  mode. Note that the drain-source breakdown voltage is lowered in this mode.

## 5.2. Dynamic Characteristics (Unless otherwise specified, Ta = 25 °C)

| Characteristics                | Symbol           | Test Condition   | Min | Тур. | Max | Unit |
|--------------------------------|------------------|--|-----|------|-----|------|
| Input capacitance              | C <sub>iss</sub> | V <sub>DS</sub> = -10 V, V <sub>GS</sub> = 0 V,                                      | _   | 330  | _   | pF   |
| Reverse transfer capacitance   | C <sub>rss</sub> | f = 1 MHz  |     | 25   | _   |      |
| Output capacitance             | C <sub>oss</sub> |  | _   | 40   | _   |      |
| Switching time (turn-on time)  | t <sub>on</sub>  | $V_{DD}$ = -30 V, $I_{D}$ = -1.0 A<br>$V_{GS}$ = 0 to -4.5 V, $R_{G}$ = 10 $\Omega$  |     | 29   | _   | ns   |
| Switching time (turn-off time) | t <sub>off</sub> | Duty $\leq$ 1 %, $V_{IN}$ : $t_r$ , $t_f$ < 5 ns,<br>Common source, See Chapter 5.3. |     | 48   |     |      |

#### 5.3. Switching Time Test Circuit



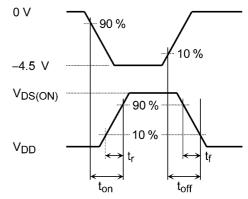


Fig. 5.3.1 Switching Time Test Circuit

Fig. 5.3.2 Input Waveform/Output Waveform

#### 5.4. Gate Charge Characteristics (Unless otherwise specified, T<sub>a</sub> = 25 °C)

| Characteristics                                 | Symbol           | Test Condition                                    | Min | Тур. | Max | Unit |
|---|------------------|---|-----|------|-----|------|
| Total gate charge (gate-source plus gate-drain) | Qg               | $V_{DD} = -48 \text{ V}, V_{GS} = -10 \text{ V},$ | _   | 8.3  | _   | nC   |
| Gate-source charge 1                            | Q <sub>gs1</sub> | $I_D = -2.0 \text{ A}$                            | _   | 0.8  |     |      |
| Gate-drain charge                               | Q <sub>gd</sub>  |   | _   | 1.7  | _   |      |

Note 2: Pulse measurement.

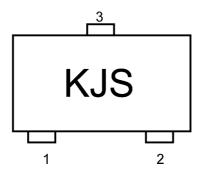


## 5.5. Source-Drain Characteristics (Unless otherwise specified, Ta = 25 °C)

| Characteristics       |          | Symbol    | Test Condition                                | Min | Тур. | Max | Unit |
|-----------------------|----------|-----------|---|-----|------|-----|------|
| Diode forward voltage | (Note 1) | $V_{DSF}$ | I <sub>D</sub> = 2.0 A, V <sub>GS</sub> = 0 V |     | 0.9  | 1.2 | V    |

Note 1: Pulse measurement.

## 6. Marking





#### 7. Characteristics Curves (Note)

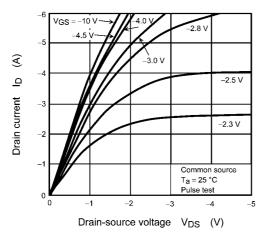


Fig. 7.1  $I_D - V_{DS}$ 

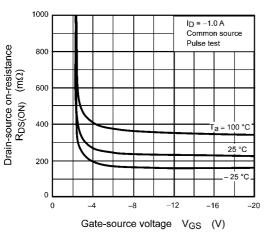


Fig. 7.3 R<sub>DS(ON)</sub> - V<sub>GS</sub>

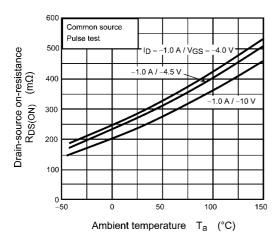


Fig. 7.5 R<sub>DS(ON)</sub> - T<sub>a</sub>

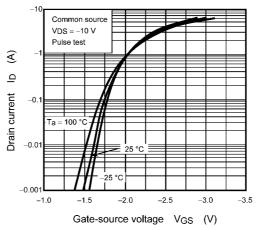


Fig. 7.2  $I_D - V_{GS}$ 

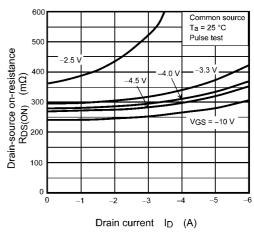


Fig. 7.4 R<sub>DS(ON)</sub> - I<sub>D</sub>

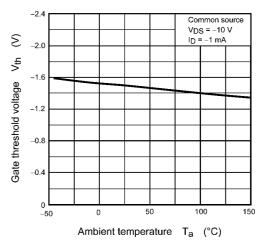


Fig. 7.6 V<sub>th</sub> - T<sub>a</sub>

Rev.3.0



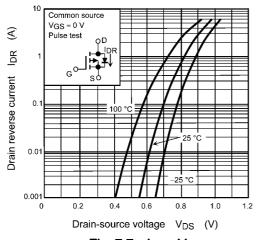


Fig. 7.7 I<sub>DR</sub> - V<sub>DS</sub>

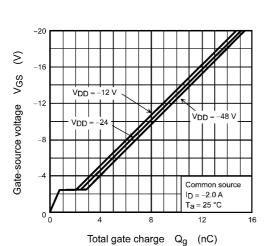


Fig. 7.9 Dynamic Input Characteristics

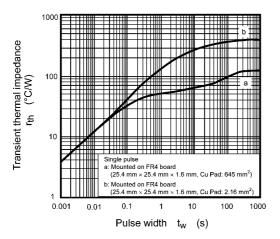


Fig. 7.11 rth - tw

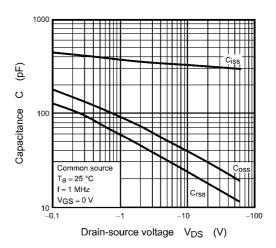


Fig. 7.8 C - V<sub>DS</sub>

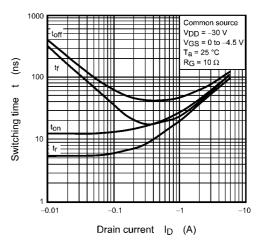


Fig. 7.10 t - I<sub>D</sub>

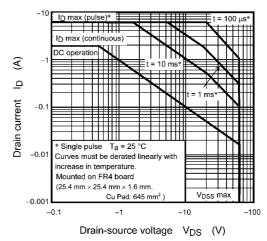


Fig. 7.12 Safe Operating Area



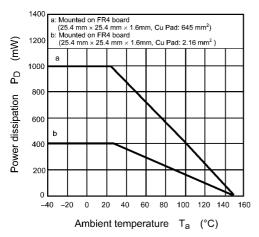


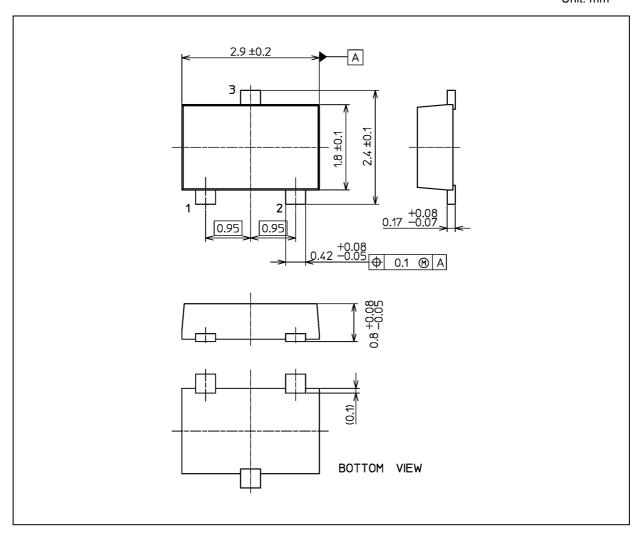
Fig. 7.13 PD - Ta

Note: The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



## **Package Dimensions**

Unit: mm



Weight: 0.011 g (typ.)

|                   | Package Name(s) |
|-------------------|-----------------|
| TOSHIBA: 2-3Z1S   |                 |
| Nickname: SOT-23F |                 |



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